



ESD



TVS



TSS



MOV



GDT



PLED

KBP2005-MS THRU KBP210-MS Product specification

VOLTAGE RANGE: 50 - 1000V
CURRENT: 2.0 A

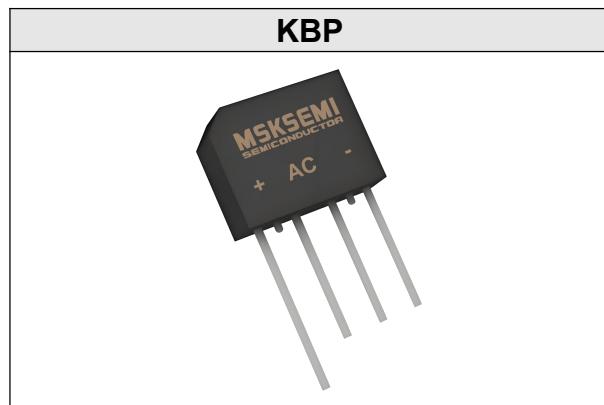
FEATURES

- Diffused Junction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards

MECHANICAL DATA

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 1.7 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

REFERENCE NEWS



Marking

KBP2005-MS	KBP201-MS	KBP202-MS	KBP204-MS
			
KBP206-MS	KBP208-MS	KBP210-MS	
			

Maximum Ratings and Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

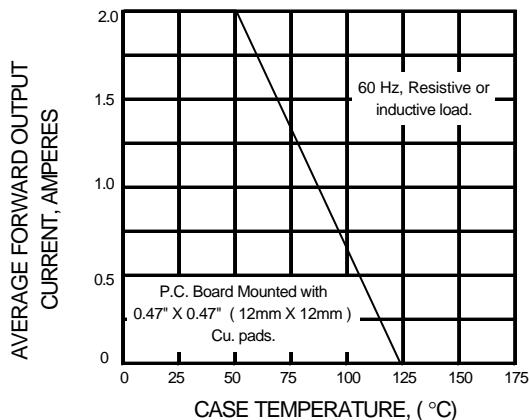
Characteristic	Symbol	KBP 200-MS	KBP 201-MS	KBP 202-MS	KBP 204-MS	KBP 206-MS	KBP 208-MS	KBP 210-MS	Unit
Peak Repetitive Reverse Voltage	V _{RRM}								
Working Peak Reverse Voltage	V _{RWM}	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V _R								
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1) $\text{@} T_A = 50^\circ\text{C}$	I _o								A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}								A
Forward Voltage (per element) $\text{@} I_F = 2.0\text{A}$	V _{FM}								V
Peak Reverse Current $\text{@} T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage $\text{@} T_A = 100^\circ\text{C}$	I _{RM}				10	500			μA
Rating for Fusing (t<8.3ms)	I _{2t}								A^2s
Typical Junction Capacitance per element (Note 2)	C _j				25				pF
Typical Thermal Resistance (Note 3)	R _{θJA}				30				K/W
Operating and Storage Temperature Range	T _j , T _{STG}						-55 to +165		°C

Note:

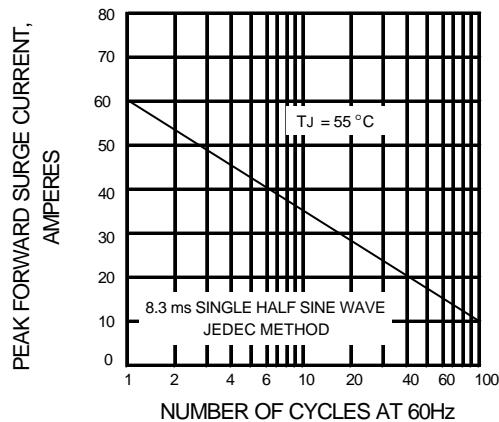
1. Leads maintained at ambient temperature at a distance of 9.5mm from the case.
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.
3. Thermal resistance junction to ambient mounted on PC board with 12mm² copper pad.

RATING AND CHARACTERISTIC CURVES (KBP200-MS THRU KBP210-MS)

**FIG.1 - DERATING CURVE FOR OUTPUT
RECTIFIED CURRENT**



**FIG.2 - MAXIMUM NON-REPETITIVE PEAK
FORWARD SURGE CURRENT**



**FIG.3 - TYPICAL FORWARD CHARACTERISTICS
PER DIODE**

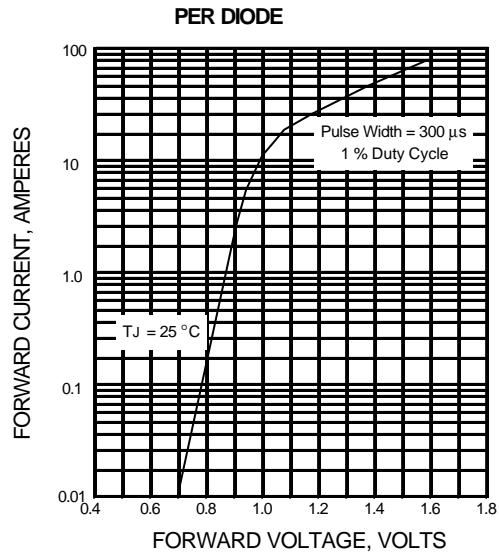
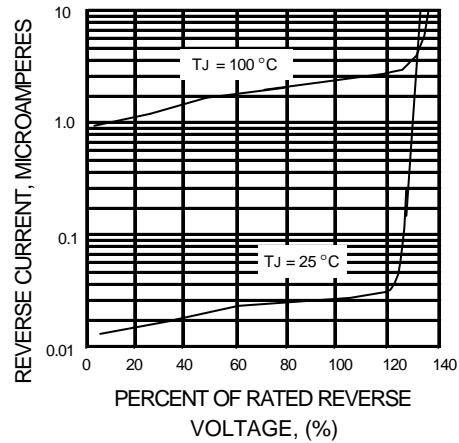
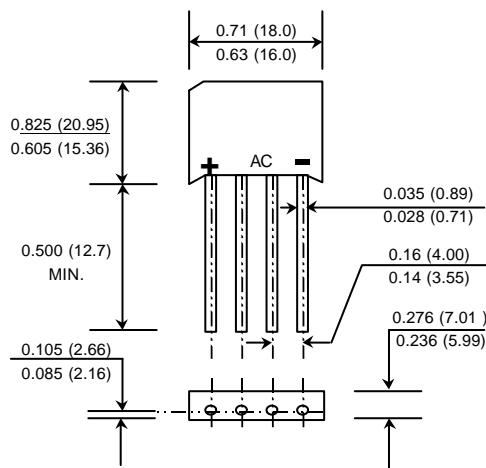


FIG.4 - TYPICAL REVERSE CHARACTERISTICS



PACKAGE MECHANICAL DATA**REELSPECIFICATION**

P/N	PKG	QTY
KBP2005-MS THRU KBP210-MS	KBP	500

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